

LNJ115W8HRA

Surface Mounting Chip LED

TSS Bi-Color Type

■ Absolute Maximum Ratings $T_a = 25^\circ\text{C}$

• Blue

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	40	mW
Forward current	I_F	10	mA
Pulse forward current *	I_{FP}	50	mA
Reverse voltage	V_R	5	V
Operating ambient temperature	T_{opr}	-30 to +85	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Lighting Color / Lens Color

- Blue / White Diffused
- Red / White Diffused

• Red

Parameter	Symbol	Rating	Unit
Power dissipation	P_D	55	mW
Forward current	I_F	20	mA
Pulse forward current *	I_{FP}	60	mA
Reverse voltage	V_R	3	V
Operating ambient temperature	T_{opr}	-30 to +80	$^\circ\text{C}$
Storage temperature	T_{stg}	-40 to +100	$^\circ\text{C}$

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

■ Electro-Optical Characteristics $T_a = 25^\circ\text{C}$

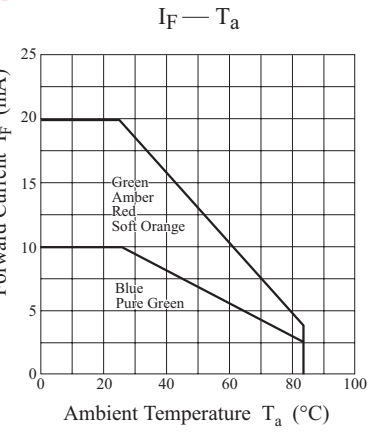
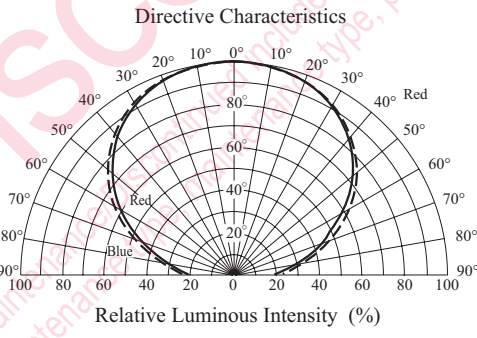
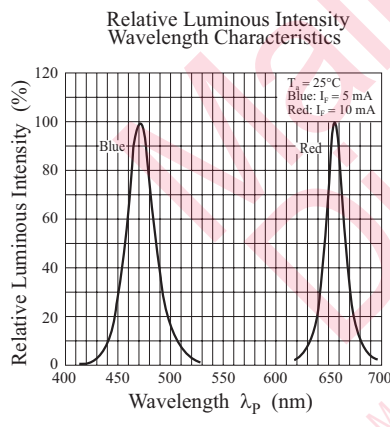
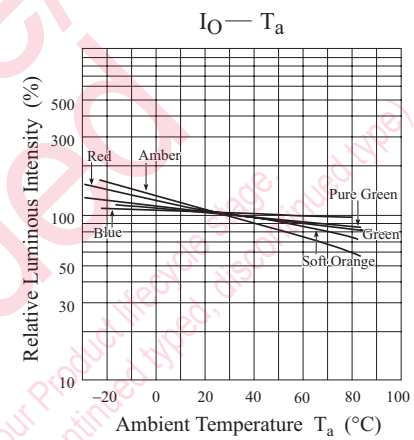
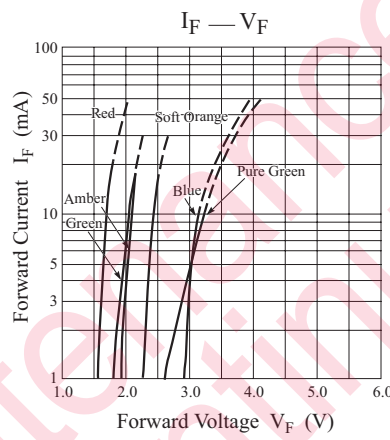
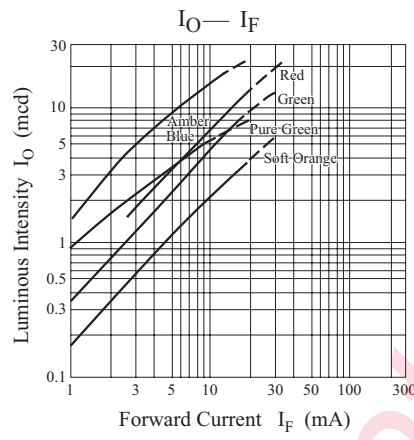
• Blue

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O		4.0	8.4		mcd
Forward current	I_F			5		mA
Forward voltage	V_F	$I_F = 5\text{ mA}$		3.2	3.7	V
Peak emission wavelength	λ_p	$I_F = 5\text{ mA}$		470		nm
Spectral half band width	$\Delta\lambda$	$I_F = 5\text{ mA}$		30		nm
Reverse current	I_R	$V_R = 5\text{ V}$			10	μA

■ Electro-Optical Characteristics (Continued) $T_a = 25^\circ\text{C}$

• Red

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Luminous intensity	I_O		2.8	6.7		mcd
Forward current	I_F			10		mA
Forward voltage	V_F	$I_F = 10\text{ mA}$		1.72	2.6	V
Peak emission wavelength	λ_P	$I_F = 10\text{ mA}$		655		nm
Spectral half band width	$\Delta\lambda$	$I_F = 10\text{ mA}$		20		nm
Reverse current	I_R	$V_R = 3\text{ V}$			100	μA



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